

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	18145	chip adj1 chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:31
L2	2239	predetermin\$2 with (amount volume) with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:32
L3	904	predetermin\$2 near3 (amount volume) near3 adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:33
L4	15	1 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:40
L5	24	3 with thickness	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:33
L6	132	2 with thickness	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:34
L7	2	1 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:34
L8	7071	(second near2 (chip die (semiconduct\$3 near (device element package)))) near3 (mount\$3 bond\$3 stack\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:42

L9	24	2 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 15:42
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